



**flowDUAL E1 SiC**

**1200 V / 15 mΩ**

**Topology features**

- Temperature sensor
- Half Bridge

**Component features**

- High Blocking Voltage with low drain source on state resistance
- High speed SiC-MOSFET technology
- Resistant to Latch-up

**Housing features**

- Base isolation: Al<sub>2</sub>O<sub>3</sub>
- Convex shaped substrate for superior thermal contact
- Compact housing
- CTI600 housing material
- Thermo-mechanical push-and-pull force relief
- Press-fit pin
- Reliable cold welding connection

**Target applications**

- Charging Stations
- Energy Storage Systems
- General
- Industrial Drives
- Power Supply
- Servo Drives
- Solar Inverters
- UPS

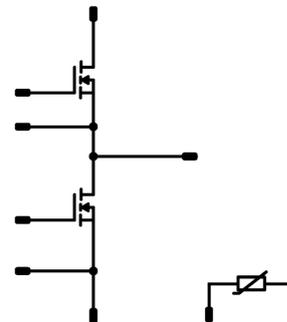
**Types**

- 10-EZ122PA015MS-LJ67F78T

**flow E1 12 mm housing**



**Schematic**





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## Maximum Ratings

$T_j = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
<b>Inverter Switch</b>				
Drain-source voltage	$V_{DS}$		1200	V
Drain current (DC current)	$I_D$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	87	A
Peak drain current	$I_{DM}$	$t_p$ limited by $T_{jmax}$	320	A
Total power dissipation	$P_{tot}$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	166	W
Gate-source voltage	$V_{GS}$	static	-5 / 18	V
		dynamic	-10 / 22	V
Maximum Junction Temperature	$T_{jmax}$		175	°C

## Module Properties

### Thermal Properties

Storage temperature	$T_{stg}$		-40...+125	°C
Operation temperature under switching condition	$T_{jop}$		-40...+( $T_{jmax} - 25$ )	°C

### Isolation Properties

Isolation voltage	$V_{isol}$	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
Creepage distance			>12,7	mm
Clearance			8,62	mm
Comparative Tracking Index	CTI		≥ 600	

\*100 % tested in production



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### Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		$V_{GE}$ [V] $V_{GS}$ [V]	$V_{CE}$ [V] $V_{DS}$ [V] $V_F$ [V]	$I_C$ [A] $I_D$ [A] $I_F$ [A]	$T_j$ [°C]	Min	Typ	Max		

#### Inverter Switch

##### Static

Drain-source on-state resistance	$r_{DS(on)}$	18		80	25 125 150		14,8 18,5 20,4	22,5 <sup>(1)</sup>	mΩ
Gate-source threshold voltage	$V_{GS(th)}$			0,008	25	1,7	2,25	2,75	V
Gate to Source Leakage Current	$I_{GSS}$	22	0		25			200	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	0	1200		25			20	μA
Internal gate resistance	$r_g$						1		Ω
Gate charge	$Q_g$	-5/18	800	80	25		216		nC
Short-circuit input capacitance	$C_{iss}$	$f = 500$ kHz	0	800	0	25		5200	pF
Short-circuit output capacitance	$C_{oss}$							270	
Reverse transfer capacitance	$C_{rss}$							12	
Diode forward voltage	$V_{SD}$	0		80	25		4,1		V

##### Thermal

Thermal resistance junction to sink <sup>(2)</sup>	$R_{th(j-s)}$	$\lambda_{paste} = 5,2$ W/mK (PTM)					0,57		K/W
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10-EZ122PA015MS-LJ67F78T  
datasheet

### Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		$V_{GE}$ [V] $V_{GS}$ [V]	$V_{CE}$ [V] $V_{DS}$ [V] $V_F$ [V]	$I_C$ [A] $I_D$ [A] $I_F$ [A]	$T_j$ [°C]	Min	Typ	Max		
<b>Dynamic</b>										
Turn-on delay time	$t_{d(on)}$					25 125 150		40,95 45,76 44,28		ns
Rise time	$t_r$	$R_{gon} = 8 \Omega$ $R_{goff} = 8 \Omega$				25 125 150		26,13 20,66 20,2		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		75,98 88,65 91,17		ns
Fall time	$t_f$					25 125 150		14,06 12,26 11,42		ns
Turn-on energy (per pulse)	$E_{on}$	$Q_{rFWD}=0,345 \mu C$ $Q_{rFWD}=1,1 \mu C$ $Q_{rFWD}=1,32 \mu C$				25 125 150		1,77 1,85 1,91		mWs
Turn-off energy (per pulse)	$E_{off}$		-5/18	600	80	25 125 150		0,449 0,501 0,511		mWs
Peak recovery current	$I_{RRM}$					25 125 150		31,14 56,86 64,83		A
Reverse recovery time	$t_{rr}$					25 125 150		19,41 30,96 32		ns
Recovered charge	$Q_r$	$di/dt=3585 A/\mu s$ $di/dt=4277 A/\mu s$ $di/dt=4335 A/\mu s$				25 125 150		0,345 1,1 1,32		$\mu C$
Reverse recovered energy	$E_{rec}$					25 125 150		0,04 0,231 0,272		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		4041,86 4072,4 5110,61		A/ $\mu s$



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### Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		$V_{GS}$ [V]	$V_{GE}$ [V]	$V_{DS}$ [V]	$V_{CE}$ [V]	$T_j$ [°C]	Min	Typ	Max	

### Thermistor

#### Static

Rated resistance	$R$					25		5		kΩ
Deviation of R100	$A_{R/R}$	$R_{100} = 499 \Omega$				100	3,2		3,3	%
Power dissipation	$P$					25		130		mW
Power dissipation constant	$d$					25		1,3		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 1 \%$						3380		K
Vincotech Thermistor Reference									V	

<sup>(1)</sup> Value at chip level

<sup>(2)</sup> Only valid with pre-applied Vincotech thermal interface material.

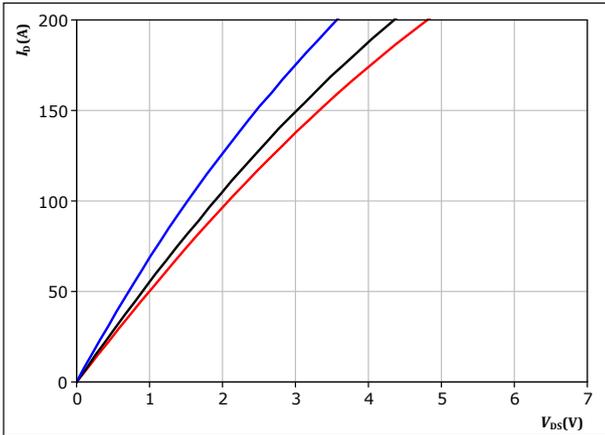


## Inverter Switch Characteristics

**figure 1.** MOSFET

Typical output characteristics

$$I_D = f(V_{DS})$$

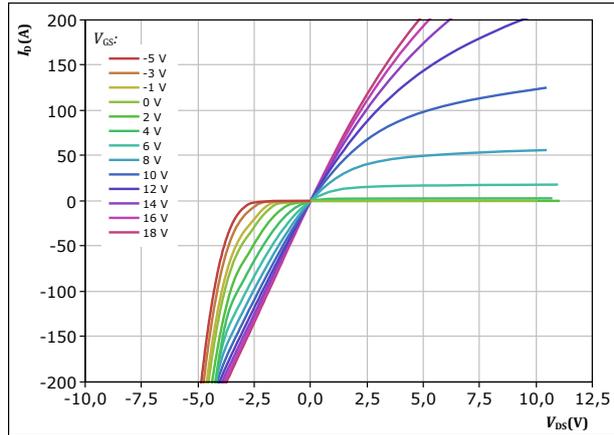


$t_p = 250 \mu s$   
 $V_{GS} = 18 V$   
 $T_j: 25 \text{ }^\circ\text{C}$   
 $125 \text{ }^\circ\text{C}$   
 $150 \text{ }^\circ\text{C}$

**figure 2.** MOSFET

Typical output characteristics

$$I_D = f(V_{DS})$$

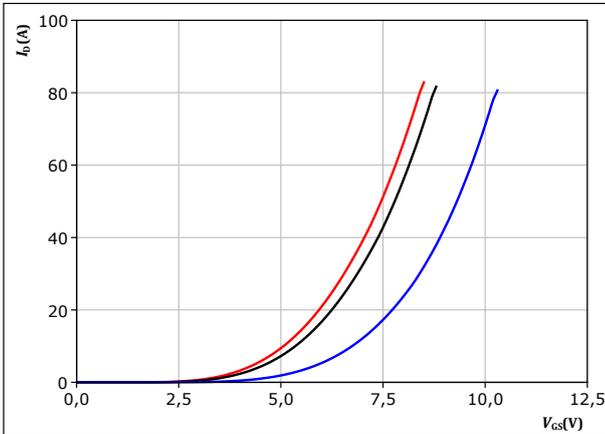


$t_p = 250 \mu s$   
 $T_j = 150 \text{ }^\circ\text{C}$   
 $V_{GS}$  from -5 V to 18 V in steps of 2 V

**figure 3.** MOSFET

Typical transfer characteristics

$$I_D = f(V_{GS})$$

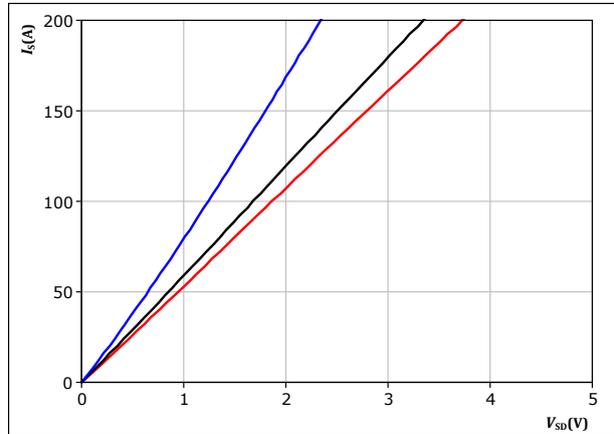


$t_p = 250 \mu s$   
 $V_{DS} = 30 V$   
 $T_j: 25 \text{ }^\circ\text{C}$   
 $125 \text{ }^\circ\text{C}$   
 $150 \text{ }^\circ\text{C}$

**figure 4.** MOSFET

Typical reverse drain current characteristics

$$I_{SD} = f(V_{SD})$$



$t_p = 250 \mu s$   
 $V_{GS} = 18 V$   
 $T_j: 25 \text{ }^\circ\text{C}$   
 $125 \text{ }^\circ\text{C}$   
 $150 \text{ }^\circ\text{C}$

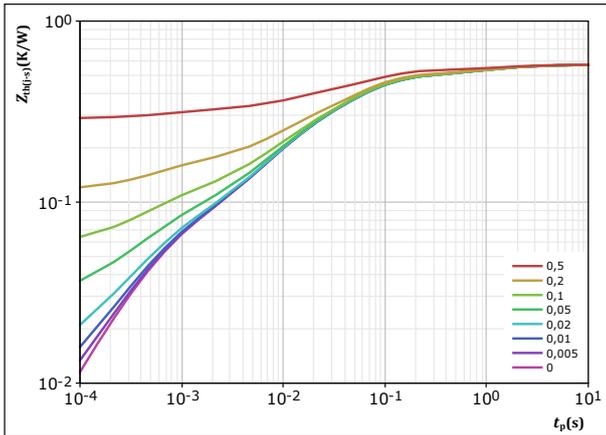


## Inverter Switch Characteristics

**figure 5.** MOSFET

Transient thermal impedance as a function of pulse width

$$Z_{th(j-c)} = f(t_p)$$



$$D = \frac{t_p}{T}$$

$$R_{th(j-c)} = 0,574 \text{ K/W}$$

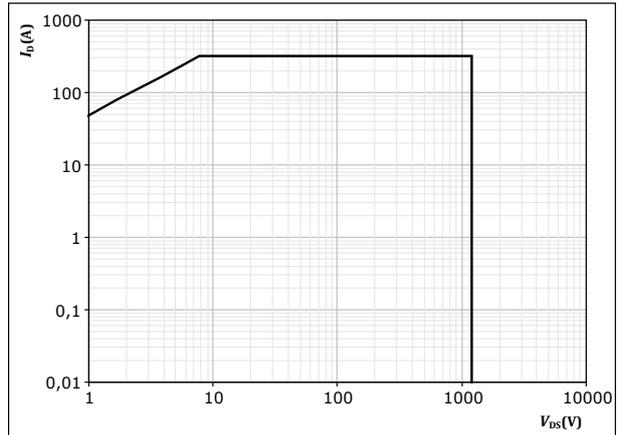
MOSFET thermal model values

R (K/W)	$\tau$ (s)
1,49E-02	7,19E+00
7,90E-02	9,10E-01
2,88E-01	5,48E-02
1,41E-01	8,91E-03
5,45E-02	5,28E-04

**figure 6.** MOSFET

Safe operating area

$$I_D = f(V_{DS})$$



D = single pulse

$$T_s = 80 \text{ } ^\circ\text{C}$$

$$V_{GS} = 18 \text{ V}$$

$$T_i = T_{jmax}$$

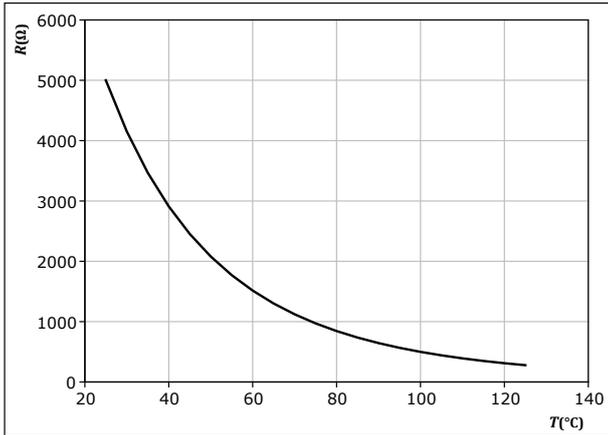


### Thermistor Characteristics

figure 7. Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$

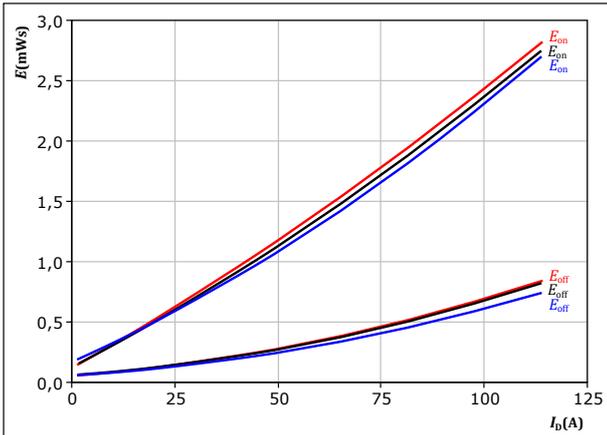




## Inverter Switching Characteristics

figure 8. MOSFET

Typical switching energy losses as a function of drain current  
 $E = f(I_D)$

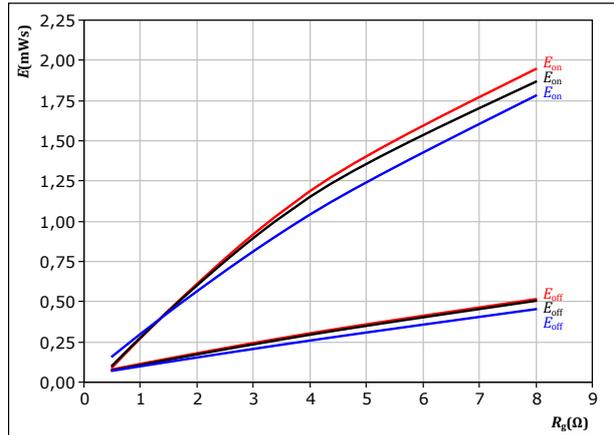


With an inductive load at  
 $V_{DS} = 600 \text{ V}$   
 $V_{GS} = -5/18 \text{ V}$   
 $R_{gon} = 8 \text{ } \Omega$   
 $R_{goff} = 8 \text{ } \Omega$

$T_j$ : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 9. MOSFET

Typical switching energy losses as a function of MOSFET turn on gate resistor  
 $E = f(R_g)$

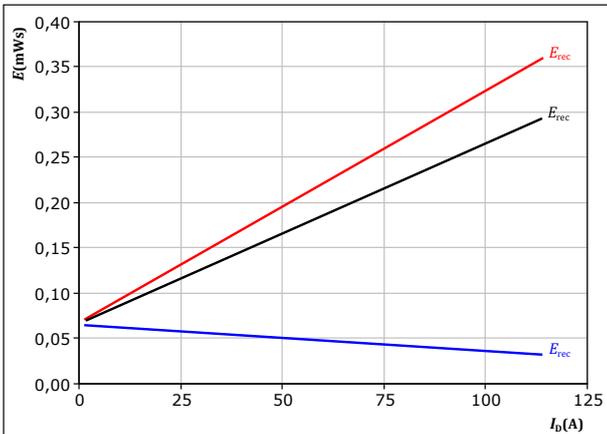


With an inductive load at  
 $V_{DS} = 600 \text{ V}$   
 $V_{GS} = -5/18 \text{ V}$   
 $I_D = 80 \text{ A}$

$T_j$ : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 10. MOSFET

Typical reverse recovered energy loss as a function of drain current  
 $E_{rec} = f(I_D)$

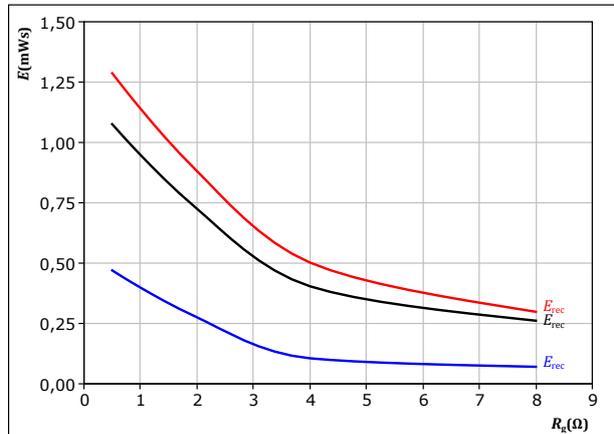


With an inductive load at  
 $V_{DS} = 600 \text{ V}$   
 $V_{GS} = -5/18 \text{ V}$   
 $R_{gon} = 8 \text{ } \Omega$

$T_j$ : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 11. MOSFET

Typical reverse recovered energy loss as a function of MOSFET turn on gate resistor  
 $E_{rec} = f(R_g)$



With an inductive load at  
 $V_{DS} = 600 \text{ V}$   
 $V_{GS} = -5/18 \text{ V}$   
 $I_D = 80 \text{ A}$

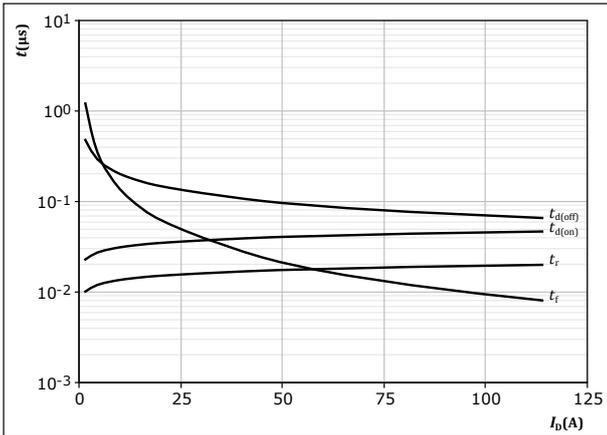
$T_j$ : 25 °C (blue), 125 °C (black), 150 °C (red)



## Inverter Switching Characteristics

**figure 12.** MOSFET

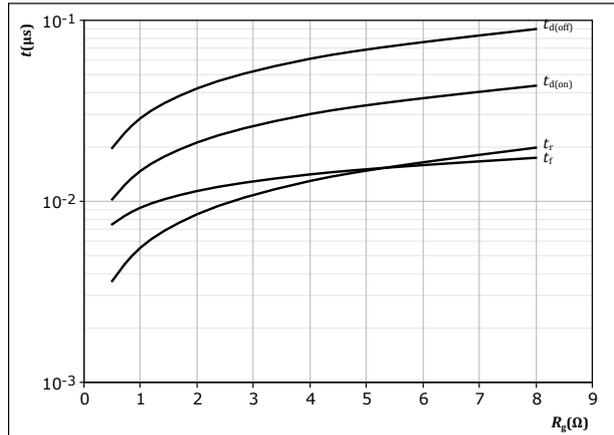
Typical switching times as a function of drain current  
 $t = f(I_D)$



With an inductive load at  
 $T_j = 150 \text{ }^\circ\text{C}$   
 $V_{DS} = 600 \text{ V}$   
 $V_{GS} = -5/18 \text{ V}$   
 $R_{gon} = 8 \text{ } \Omega$   
 $R_{goff} = 8 \text{ } \Omega$

**figure 13.** MOSFET

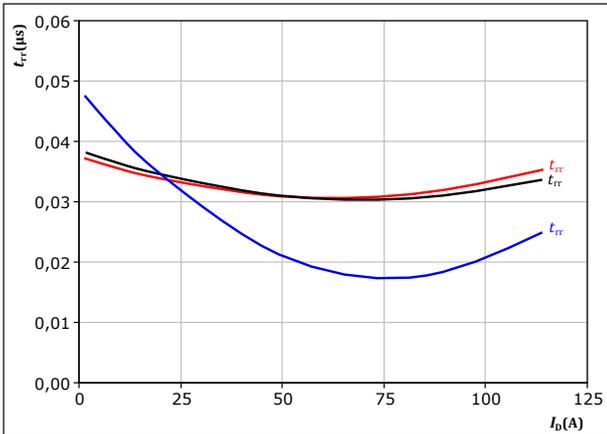
Typical switching times as a function of MOSFET turn on gate resistor  
 $t = f(R_g)$



With an inductive load at  
 $T_j = 150 \text{ }^\circ\text{C}$   
 $V_{DS} = 600 \text{ V}$   
 $V_{GS} = -5/18 \text{ V}$   
 $I_D = 80 \text{ A}$

**figure 14.** MOSFET

Typical reverse recovery time as a function of drain current  
 $t_{rr} = f(I_D)$

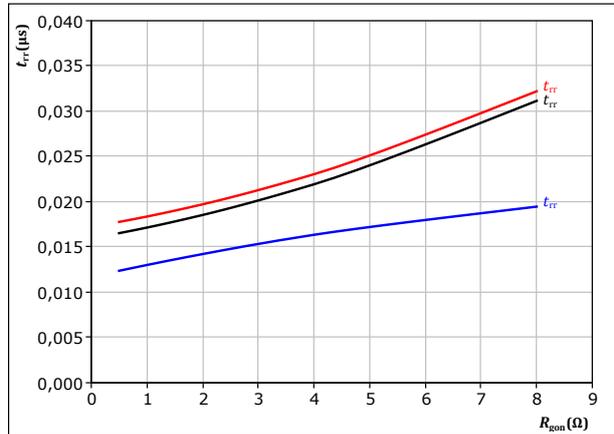


At  $V_{DS} = 600 \text{ V}$   
 $V_{GS} = -5/18 \text{ V}$   
 $R_{gon} = 8 \text{ } \Omega$

$T_j$ : — 25 °C  
 — 125 °C  
 — 150 °C

**figure 15.** MOSFET

Typical reverse recovery time as a function of MOSFET turn on gate resistor  
 $t_{rr} = f(R_{gon})$



At  $V_{DS} = 600 \text{ V}$   
 $V_{GS} = -5/18 \text{ V}$   
 $I_D = 80 \text{ A}$

$T_j$ : — 25 °C  
 — 125 °C  
 — 150 °C

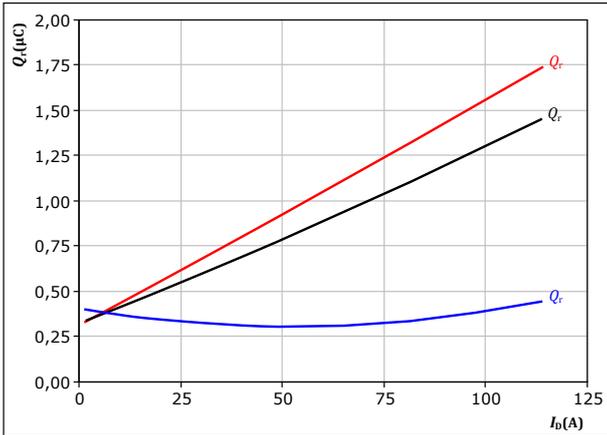


## Inverter Switching Characteristics

**figure 16.** MOSFET

Typical recovered charge as a function of drain current

$$Q_r = f(I_D)$$



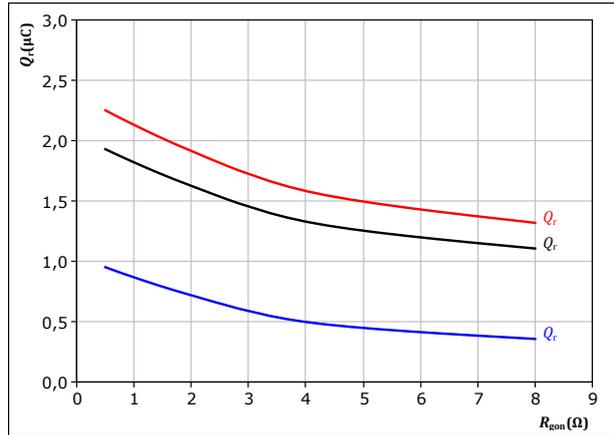
At  $V_{DS} = 600$  V  
 $V_{GS} = -5/18$  V  
 $R_{gon} = 8$   $\Omega$

$T_j$ : — 25 °C  
 — 125 °C  
 — 150 °C

**figure 17.** MOSFET

Typical recovered charge as a function of MOSFET turn on gate resistor

$$Q_r = f(R_{gon})$$



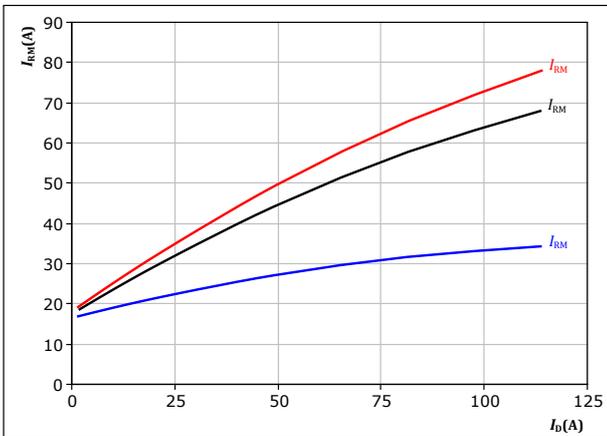
At  $V_{DS} = 600$  V  
 $V_{GS} = -5/18$  V  
 $I_D = 80$  A

$T_j$ : — 25 °C  
 — 125 °C  
 — 150 °C

**figure 18.** MOSFET

Typical peak reverse recovery current as a function of drain current

$$I_{RM} = f(I_D)$$



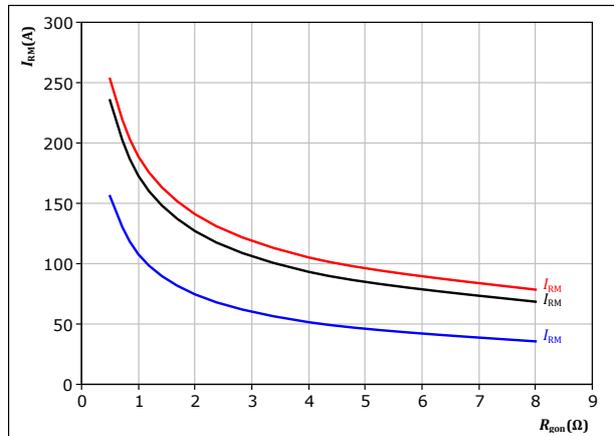
At  $V_{DS} = 600$  V  
 $V_{GS} = -5/18$  V  
 $R_{gon} = 8$   $\Omega$

$T_j$ : — 25 °C  
 — 125 °C  
 — 150 °C

**figure 19.** MOSFET

Typical peak reverse recovery current as a function of MOSFET turn on gate resistor

$$I_{RM} = f(R_{gon})$$



At  $V_{DS} = 600$  V  
 $V_{GS} = -5/18$  V  
 $I_D = 80$  A

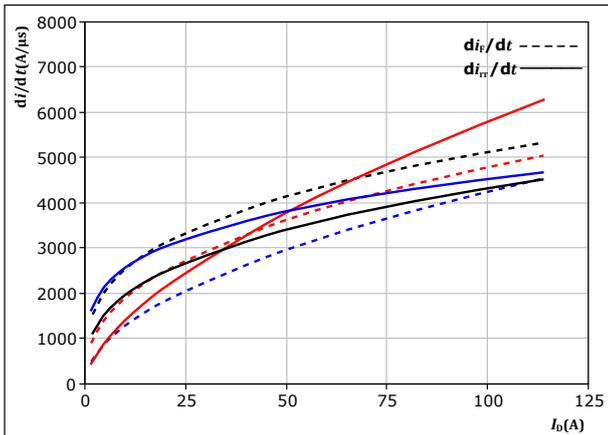
$T_j$ : — 25 °C  
 — 125 °C  
 — 150 °C



## Inverter Switching Characteristics

**figure 20.** MOSFET

Typical rate of fall of forward and reverse recovery current as a function of drain current  
 $di_f/dt, di_{rr}/dt = f(I_D)$

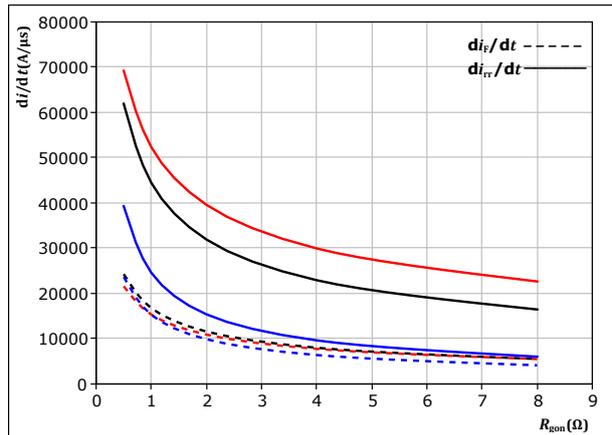


At  $V_{DS} = 600$  V  
 $V_{GS} = -5/18$  V  
 $R_{g(on)} = 8$  Ω

$T_j$ : 25 °C  
 125 °C  
 150 °C

**figure 21.** MOSFET

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor  
 $di_f/dt, di_{rr}/dt = f(R_{g(on)})$



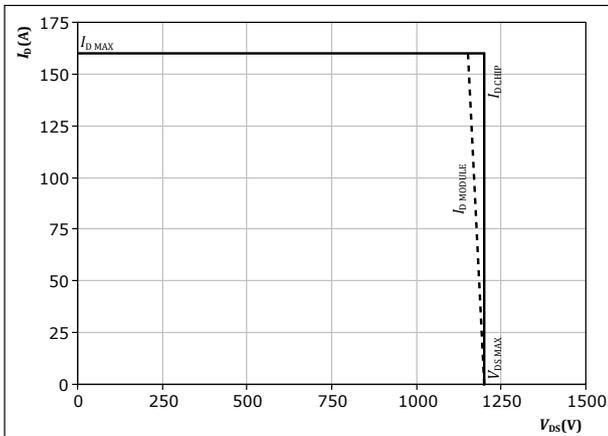
At  $V_{DS} = 600$  V  
 $V_{GS} = -5/18$  V  
 $I_D = 80$  A

$T_j$ : 25 °C  
 125 °C  
 150 °C

**figure 22.** MOSFET

Reverse bias safe operating area

$I_D = f(V_{DS})$



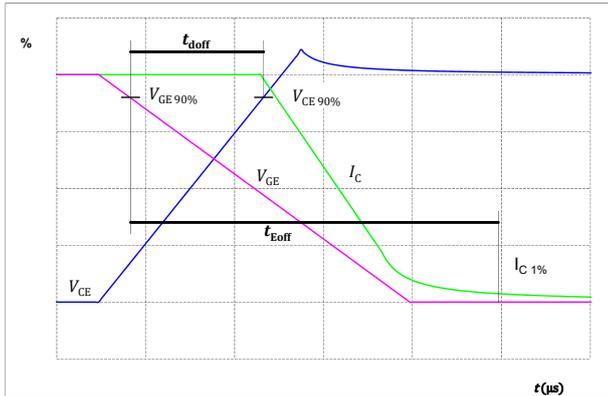
At  $T_j = 150$  °C  
 $R_{g(on)} = 8$  Ω  
 $R_{g(off)} = 8$  Ω



## Inverter Switching Definitions

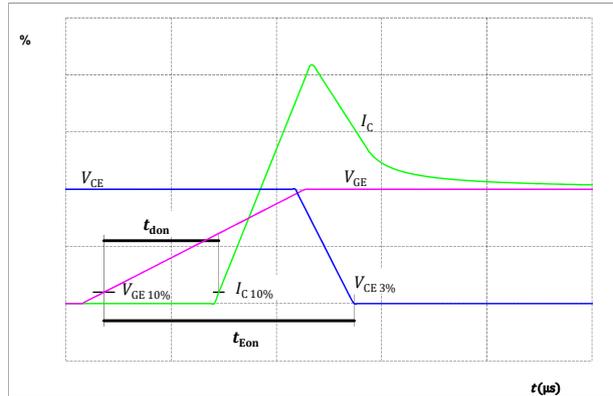
**figure 23.** MOSFET

Turn-off Switching Waveforms & definition of  $t_{doff}$   $t_{Eoff}$  ( $t_{Eoff}$  = integrating time for  $E_{off}$ )



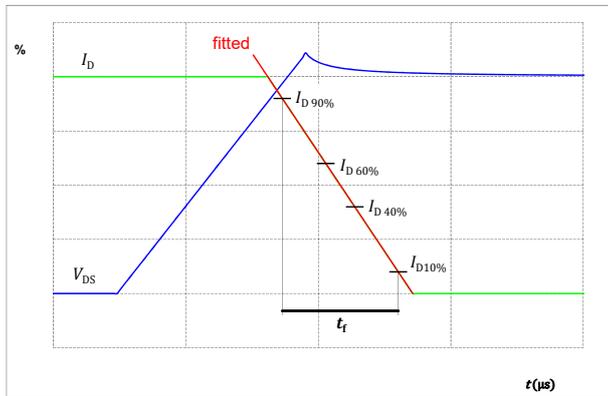
**figure 24.** MOSFET

Turn-on Switching Waveforms & definition of  $t_{don}$   $t_{Eon}$  ( $t_{Eon}$  = integrating time for  $E_{on}$ )



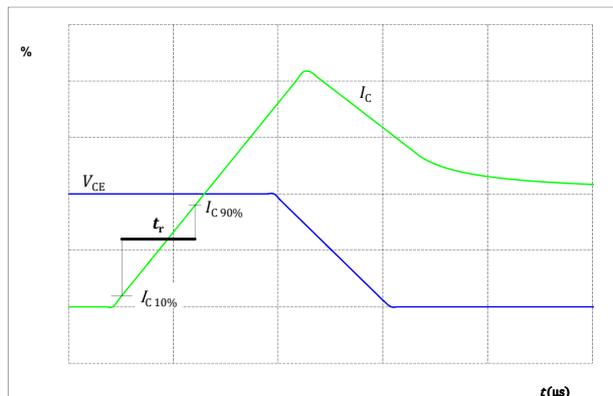
**figure 25.** MOSFET

Turn-off Switching Waveforms & definition of  $t_f$



**figure 26.** MOSFET

Turn-on Switching Waveforms & definition of  $t_r$





### Inverter Switching Definitions

figure 27. FWD

Turn-off Switching Waveforms & definition of  $t_{tr}$

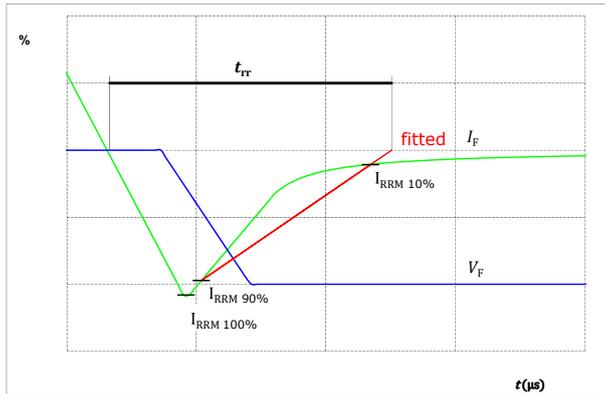


figure 28. FWD

Turn-on Switching Waveforms & definition of  $t_{Qr}$  ( $t_{Qr}$  = integrating time for  $Q_r$ )

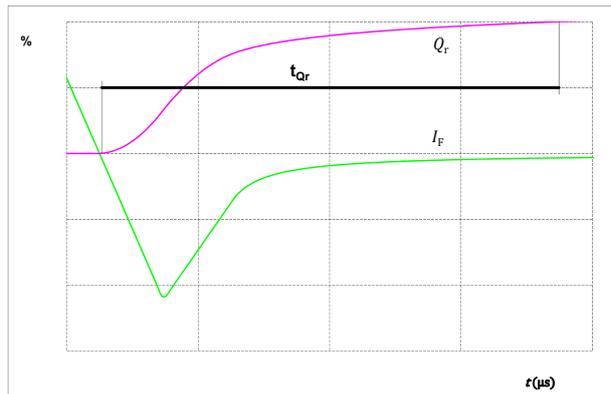
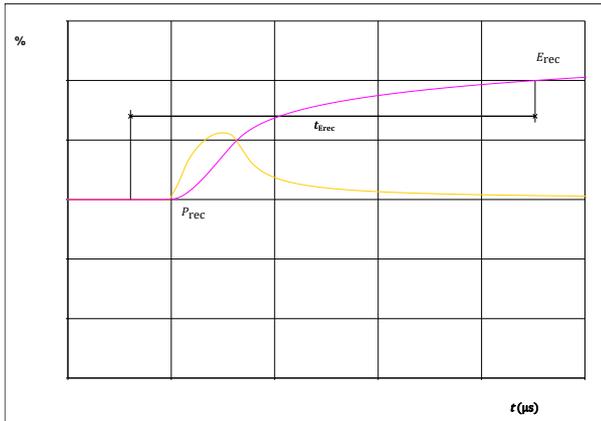


figure 29. FWD

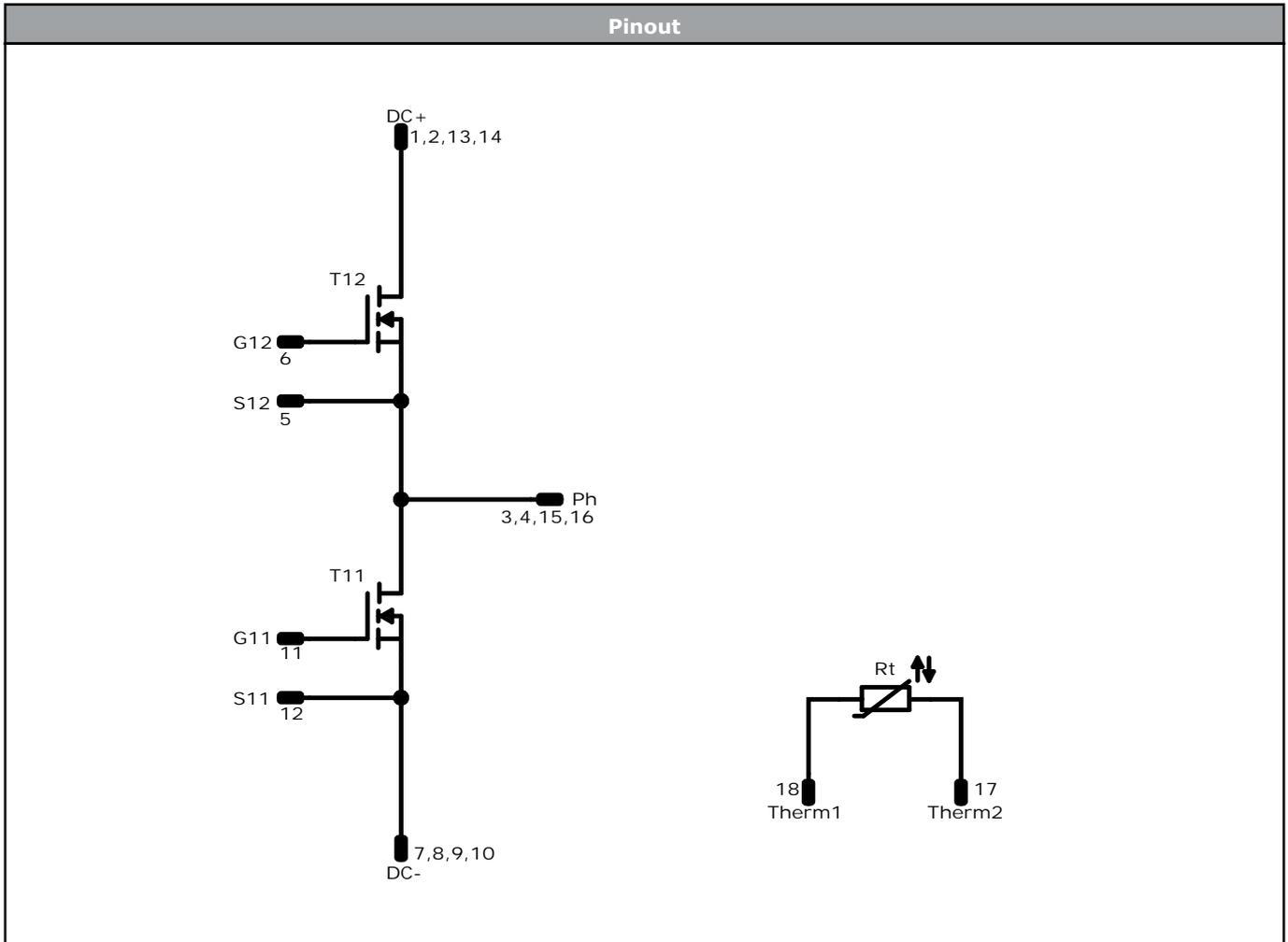
Turn-on Switching Waveforms & definition of  $t_{Erec}$  ( $t_{Erec}$  = integrating time for  $E_{rec}$ )







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Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12	MOSFET	1200 V	15 mΩ	Inverter Switch	
Rt	Thermistor			Thermistor	



Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for <i>flow</i> E1 packages see vincotech.com website.

Package data
Package data for <i>flow</i> E1 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}=175^{\circ}C$ and up to 3500VAC/1min isolation voltage. For more information see vincotech.com website.



Document No.:	Date:	Modification:	Pages
10-EZ122PA015MS-LJ67F78T-D1-14	8 Jan. 2026	Initial Release	

**DISCLAIMER**

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As used herein:

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.